

<b>Document Title</b>		<b>PACKAGE OUTLINE, 144L CSBGA, 10x10x1.4mm</b>			
<b>Doc ID #</b>	<b>21-0169</b>	<b>New Rev</b>	<b>B</b>	<b>Effective Date</b>	

<b>Originator</b>	Scott Schroeder	<b>Facility</b>	PACKAGING DEPT.		
<b>Phone #</b>	3366-2382	<b>883</b>	<input type="checkbox"/>	<b>SMD</b>	<input type="checkbox"/>
<b>ECN Type</b>	Permanent	<b>Expiration</b>	<b>Date</b>		
<b>Matl. or Masks Affected</b>	N/A	<b>Disposition</b>	N/A		

*For Fab Only*

<b>Area</b>		<b>Level</b>	<b>Class I</b>
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*For Product Related Only*

<b>Die Type</b>			
<b>External Number</b>			
<b>Business Unit</b>		<b>VP Name</b>	

*For Data Sheet Only*

<b>Print Review Req'd</b>	N/A
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*Root Cause or Justification of ECN*

Revised the ball diameter (b) dimension
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*Description of Change*

From	To
Ball diameter (b) dimension = 0.50mm nominal	Ball diameter (b) dimension = 0.45mm nominal

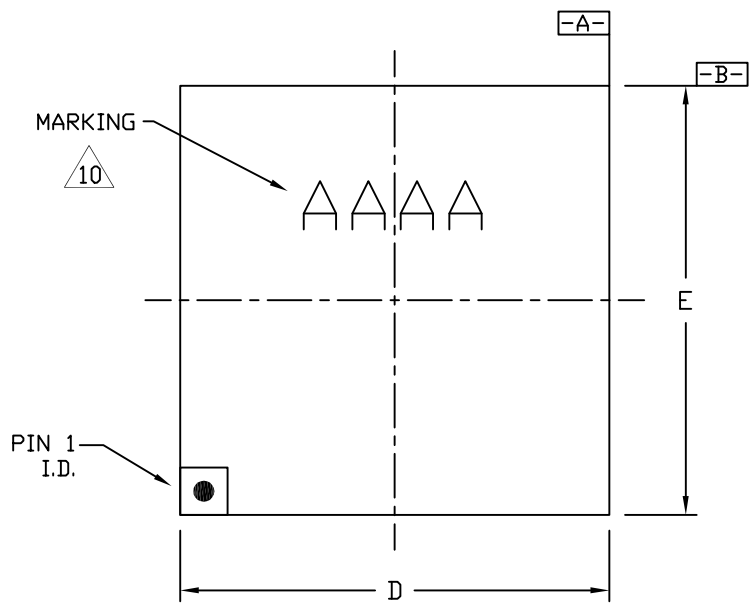
*Approvals*

Name	Functional Title	Date	Name	Functional Title	Date
Pkngng. Engr.			A. Quintero		
S. Chinnusamy					
C. Keene					

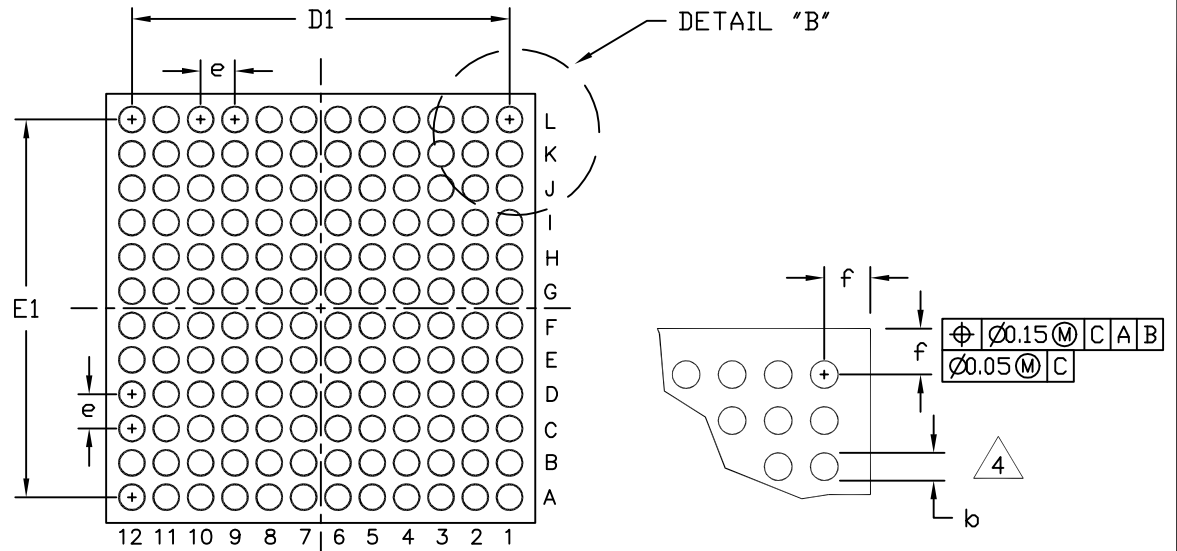
*Additional Notification (refer to 11-0001)*

HQ; Maxim North; J. Moist; L. Jackson; M. Rubenzahl; S. Sung; S. Schroeder; A. Arreola; A. Wichman; D. Goldbaum; E. Evans; Colorado/Austin/Plano Design Centers. Louis Berman; Norman Nakamura; Adolfo Ylagan.
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<b>Other Docs Affected</b> No	
<b>DC Submission Date</b>	<b>DC Processor Name</b>

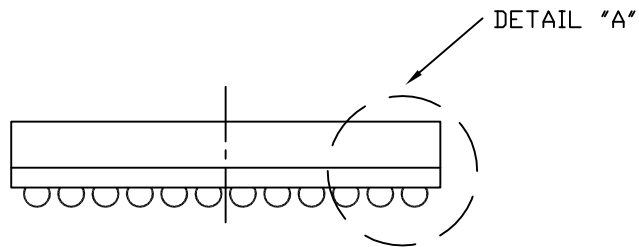


TOP VIEW

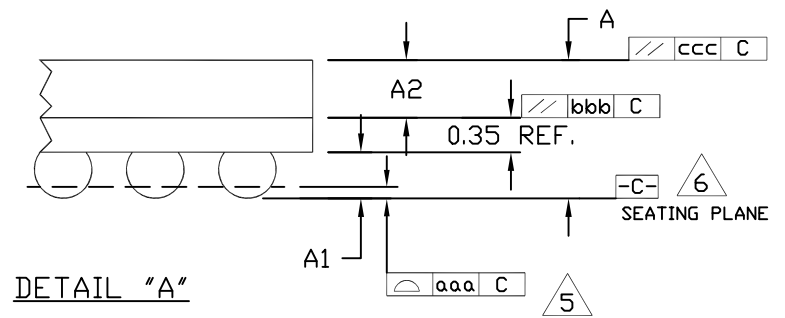


DETAIL "B"

BOTTOM VIEW



SIDE VIEW



DETAIL "A"



TITLE: PACKAGE OUTLINE,  
144L CSBGA, 10x10x1.4mm

APPROVAL	DOCUMENT CONTROL NO. 21-0169	REV. B	1/2
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-DRAWING NOT TO SCALE-

